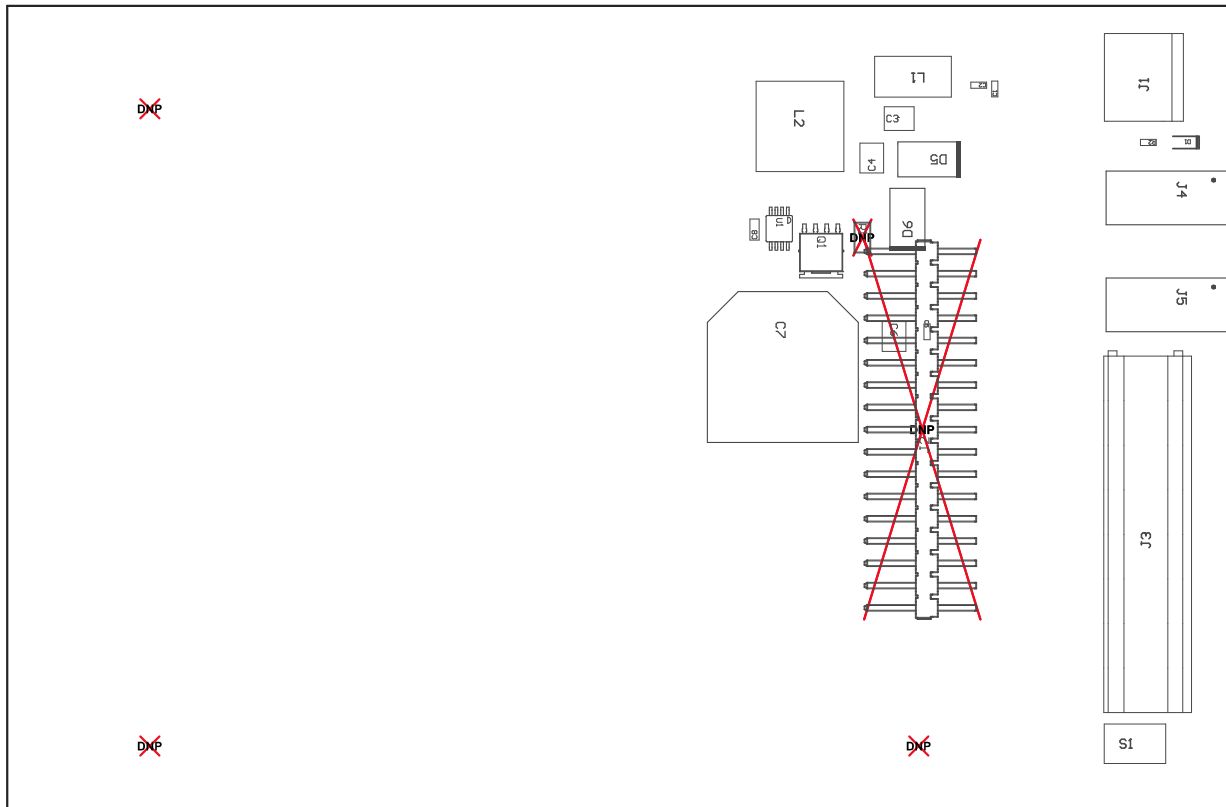
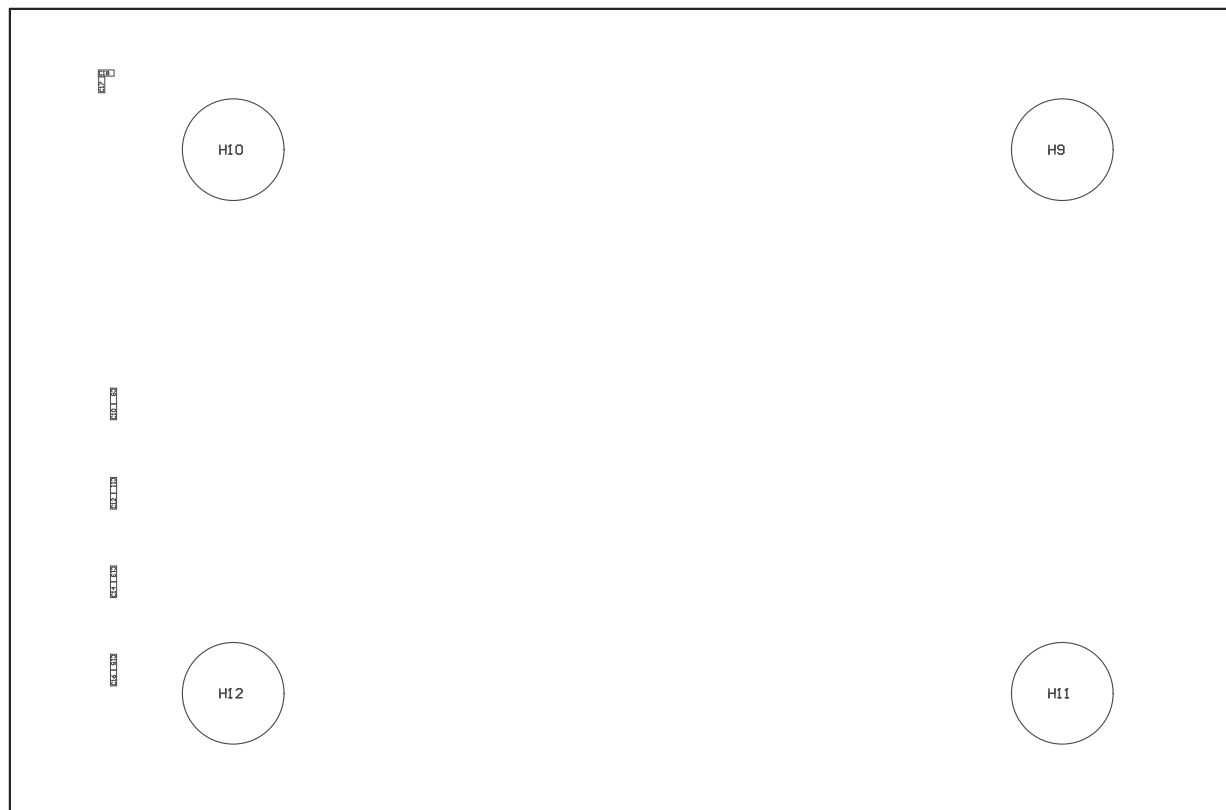


- Z21 ■Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.
- Z22 ■These assemblies are ESD sensitive, ESD precautions shall be observed.
- Z23 ■These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- Z24 ■These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.
- Z25 ■Componenets L1 and L2 are Alternate parts. Only one or the other may be placed.



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA00743_2	REV: B	SVN REV: Not In VersionControl
	TID #: TIDA-00743		
PLOT NAME = Top Assembly Drawing	GENERATED : 5/23/2017	2:15:01 PM	TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDA00743_2	REV: B	SVN REV: Not In VersionControl
	TID #: TIDA-00743		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 5/23/2017 2:15:03 PM		TEXAS INSTRUMENTS

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
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